

Surface Functionalization of Selective Laser Melted 17-4 PH by Plasma Polishing and Interstitial Diffusion Hardening for Thin Films

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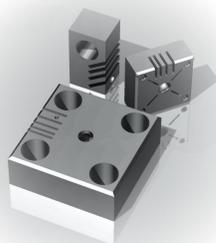
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abstract

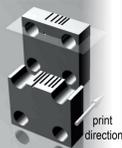
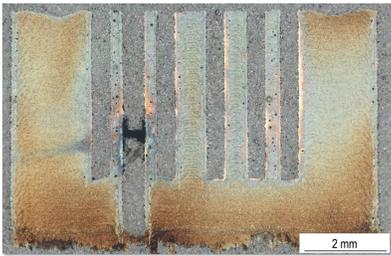
The powders used as feedstock in selective laser melting (SLM) process fundamentally limit the surface quality of these components. Particle contamination on the surfaces of the parts can remain rounded or agglomerated contributing to a very rough surface at the microscale. Furthermore, the manufacturing advantages of a closed component design lead to limitations in the mechanical finishing process, especially regarding undercuts and cavities. In addition to corrosion protection requirements, demands for wear resistance become increasingly important. This study deals with the development of a process chain for the surface functionalization of selective laser melted 17-4 PH by plasma polishing and interstitial diffusion hardening. In this context, both the leveling of the surface topography and the development of graded coating properties are of particular interest. In addition, this technology can be used to protect thin films against locally acting forces by providing sufficient support for the substrate materials.

production routine

>> Specimen Design



Optical microscopy images using Beraha-II color etchant



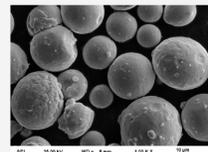
1. Selective Laser Melting

Chemical Composition of 17-4 PH in wt.%

Cr	Ni	Cu	Nb+Ta	C	Si	Mn	S	P
15-17.5	3-5	3-5	0.15-0.45	<0.07	<1	<1	<0.03	<0.04

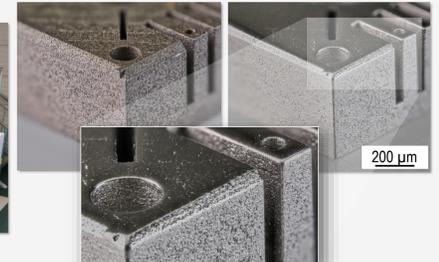
Particle Size Distribution

-53+25 μm



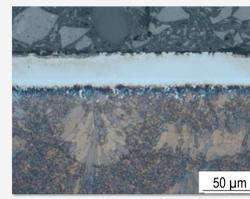
2. Plasma Polishing

As-Printed Plasma Polished



3. Thermochemical Treatment (NC)

- Gasnitrocarburization (NC)
- Temperature < 420 °C, 24 h
- Interstitially supersaturated surface layer (approx. 30 μm)



4. Thin Films (Ti_xCr_yN)

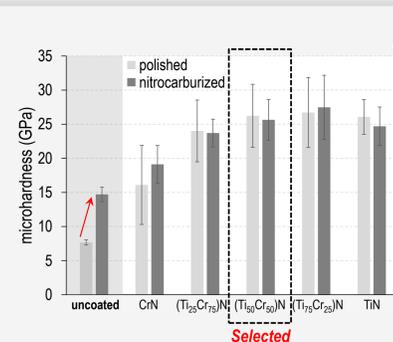
- x,y = 0, 25, 50, 100%
- Approx. 2 μm

Current Ti (A)	Current Cr (A)	Deposition time (min)	Coating Type	Coating thickness (μm)	Cr concentration (EDX at% measurement)
100	60	60	CrN	1.92	
60	105	42	(Ti ₂₅ Cr ₇₅)N	1.79	75.5
120	80	37	(Ti ₅₀ Cr ₅₀)N	1.86	45.2
150	40	42	(Ti ₇₅ Cr ₂₅)N	1.90	19.2
100		87	TiN	1.91	



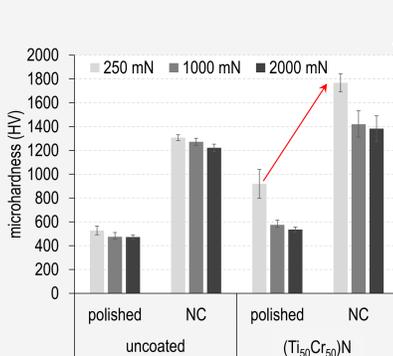
properties

Microhardness



10 mN

- Strong increase in microhardness by nitrocarburization
- Microhardness increase for thin films with high Ti content
- No influence of precondition under 10 mN

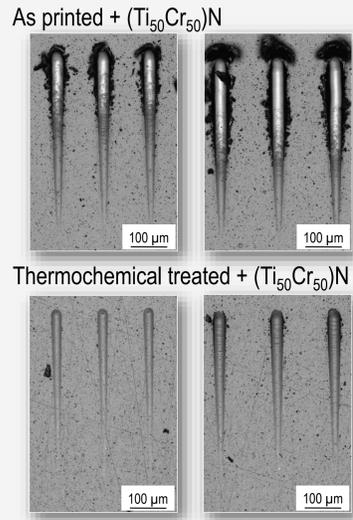
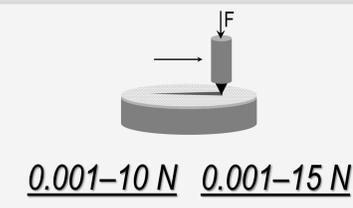


250-2000 mN

- Substrate influence by increase in indentation force
- Strong support effect of nitrocarburization

Approach confirmed

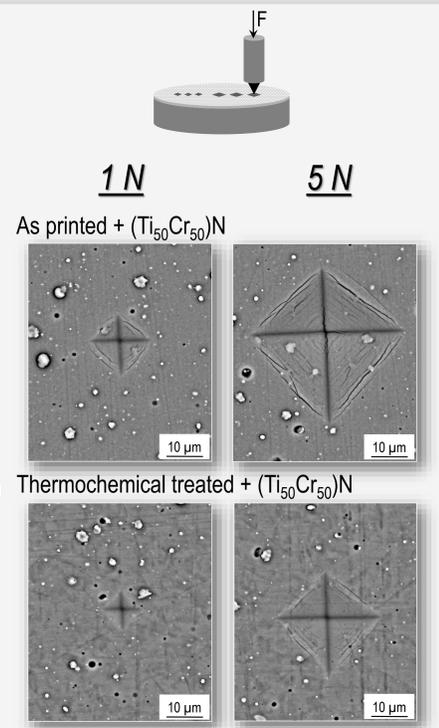
Wear and Impact Resistance



Strong increase in wear and impact resistance by thermochemical surface hardening

- Spallation of thin coatings in as printed condition
- Reduction in indentation depth
- Reduction in crack formation

Support effect of thermochemical treatment verified



summary

While plasma polishing offers appropriate potential for the formation of smooth surfaces, low-temperature diffusion processes can increase the microhardness and wear resistance by promoting a reliable support effect for thin films. This technology promises a high application potential to protect thin films with high hardness against locally acting forces. As a result, both the resilience and service life of tools can be increased.